

**49A, 55V, 0.022 Ohm, N-Channel UltraFET
Power MOSFET**



This N-Channel power MOSFET is manufactured using the innovative UltraFET™ process. This advanced process technology achieves the

lowest possible on-resistance per silicon area, resulting in outstanding performance. This device is capable of withstanding high energy in the avalanche mode and the diode exhibits very low reverse recovery time and stored charge. It was designed for use in applications where power efficiency is important, such as switching regulators, switching converters, motor drivers, relay drivers, low-voltage bus switches, and power management in portable and battery-operated products.

Formerly developmental type TA75329.

Ordering Information

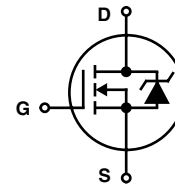
PART NUMBER	PACKAGE	BRAND
HRFZ44N	TO-220AB	HRFZ44N

NOTE: When ordering, use the entire part number.

Features

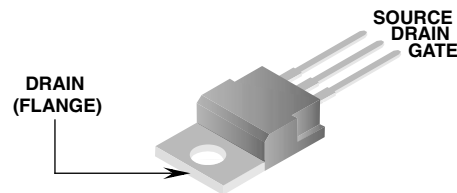
- 49A, 55V
- Simulation Models
 - Temperature Compensated PSPICE® and SABER® Electrical Models
 - Spice and Saber Thermal Impedance Models
 - www.Fairchild.com
- Peak Current vs Pulse Width Curve
- UIS Rating Curve
- Related Literature
 - TB334, "Guidelines for Soldering Surface Mount Components to PC Boards"

Symbol



Packaging

JEDEC TO-220AB



HRFZ44N

Absolute Maximum Ratings $T_C = 25^{\circ}\text{C}$, Unless Otherwise Specified

			UNITS
Drain to Source Voltage (Note 1)	V_{DSS}	55	V
Drain to Gate Voltage ($R_{GS} = 20\text{k}\Omega$) (Note 1)	V_{DGR}	55	V
Gate to Source Voltage	V_{GS}	± 20	V
Drain Current			
Continuous (Figure 2)	I_D	49	A
Pulsed Drain Current (Note 2)	I_{DM}	160	A
Pulsed Avalanche Rating	UIS	0.227	A^2s
Power Dissipation	P_D	120	W
Derate Above 25°C		0.8	$\text{W}/^{\circ}\text{C}$
Operating and Storage Temperature	T_J, T_{STG}	-55 to 175	$^{\circ}\text{C}$
Maximum Temperature for Soldering			
Leads at 0.063in (1.6mm) from Case for 10s.	T_L	300	$^{\circ}\text{C}$
Package Body for 10s, See Techbrief 334	T_{pkg}	260	$^{\circ}\text{C}$

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. $T_J = 25^{\circ}\text{C}$ to 150°C .
2. Repetitive rating: pulse width limited by maximum junction temperature.

Electrical Specifications $T_C = 25^{\circ}\text{C}$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS	
OFF STATE SPECIFICATIONS							
Drain to Source Breakdown Voltage	BV _{DSS}	I _D = 250μA, V _{GS} = 0V (Figure 11)	55	-	-	V	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 50V, V _{GS} = 0V	-	-	1	μA	
		V _{DS} = 45V, V _{GS} = 0V, T _C = 150°C	-	-	250	μA	
Gate to Source Leakage Current	I _{GSS}	V _{GS} = ±20V	-	-	±100	nA	
ON STATE SPECIFICATIONS							
Gate to Source Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = 250μA (Figure 10)	2	-	4	V	
Drain to Source On Resistance	r _{DS(ON)}	I _D = 25A, V _{GS} = 10V (Figure 9)	-	0.019	0.022	Ω	
THERMAL SPECIFICATIONS							
Thermal Resistance Junction to Case	R _{θJC}	(Figure 3)	-	-	1.25	°C/W	
Thermal Resistance Junction to Ambient	R _{θJA}	TO-220	-	-	62	°C/W	
SWITCHING SPECIFICATIONS (V _{GS} = 10V)							
Turn-On Time	t _{ON}	V _{DD} = 30V, I _D ≅ 25A, R _L = 1.2Ω, V _{GS} = 10V, R _{GS} = 9.1Ω	-	-	105	ns	
Turn-On Delay Time	t _{d(ON)}		-	12	-	ns	
Rise Time	t _r		-	58	-	ns	
Turn-Off Delay Time	t _{d(OFF)}		-	33	-	ns	
Fall Time	t _f		-	33	-	ns	
Turn-Off Time	t _{OFF}		-	-	100	ns	
GATE CHARGE SPECIFICATIONS							
Total Gate Charge	Q _{g(TOT)}	V _{GS} = 0V to 20V	V _{DD} = 30V, I _D ≅ 25A, R _L = 1.2Ω I _{g(REF)} = 1.0mA (Figure 13)	-	60	75	nC
Gate Charge at 10V	Q _{g(10)}	V _{GS} = 0V to 10V		-	35	43	nC
Threshold Gate Charge	Q _{g(TH)}	V _{GS} = 0V to 2V		-	2.0	2.5	nC
Gate to Source Gate Charge	Q _{gs}			-	4	-	nC
Gate to Drain “Miller” Charge	Q _{gd}			-	14	-	nC

HRFZ44N

Electrical Specifications $T_C = 25^\circ\text{C}$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
CAPACITANCE SPECIFICATIONS						
Input Capacitance	C_{ISS}	$V_{DS} = 25\text{V}$, $V_{GS} = 0\text{V}$, $f = 1\text{MHz}$ (Figure 12)	-	1060	-	pF
Output Capacitance	C_{OSS}		-	405	-	pF
Reverse Transfer Capacitance	C_{RSS}		-	95	-	pF

Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage	V_{SD}	$I_{SD} = 25\text{A}$	-	-	1.25	V
Reverse Recovery Time	t_{rr}	$I_{SD} = 25\text{A}$, $dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	-	72	ns
Reverse Recovered Charge	Q_{RR}	$I_{SD} = 25\text{A}$, $dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	-	120	nC

Typical Performance Curves

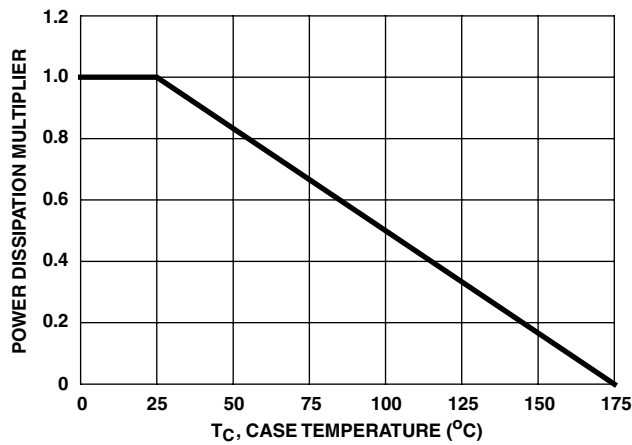


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

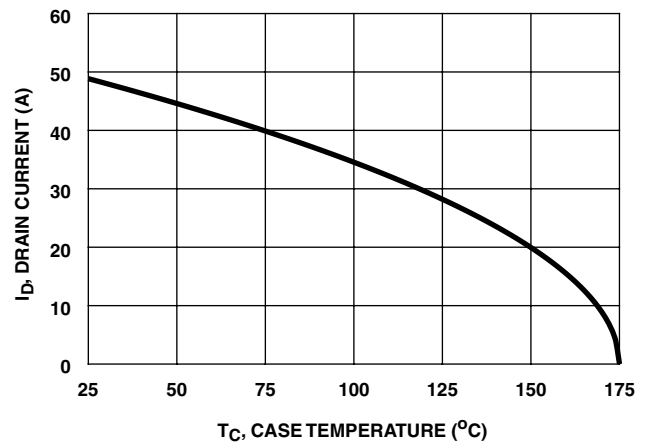


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

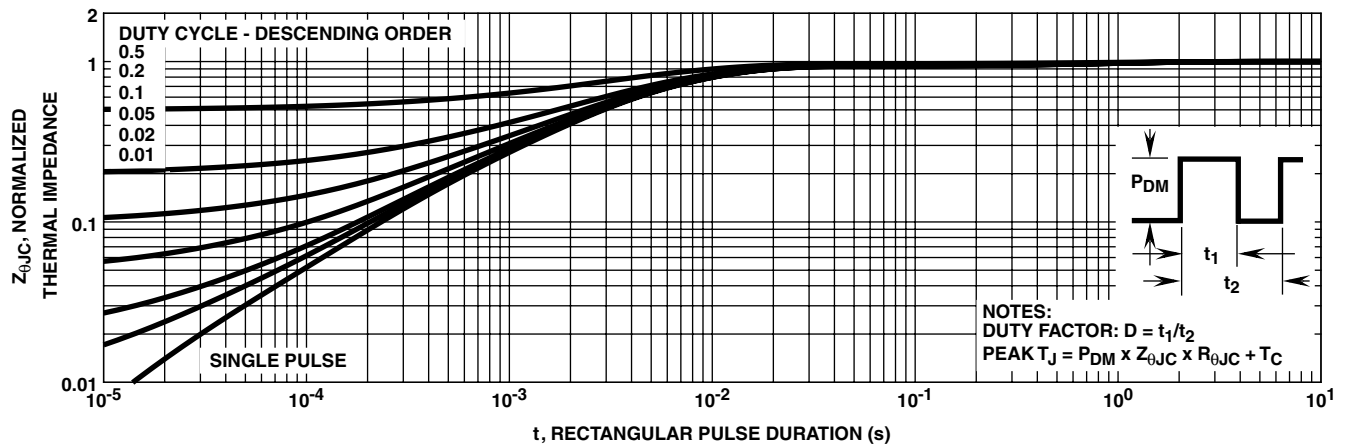


FIGURE 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE

Typical Performance Curves (Continued)

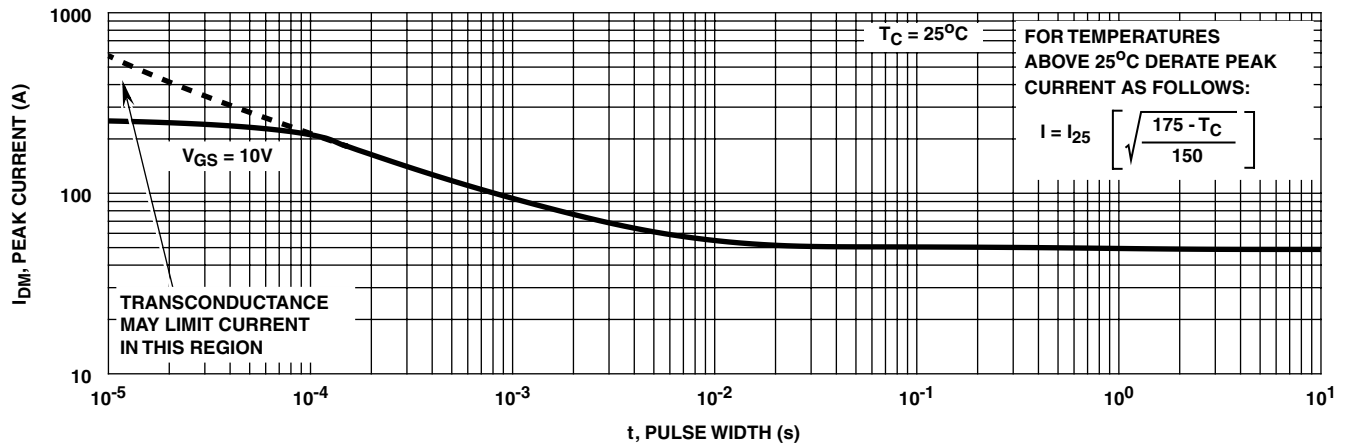


FIGURE 4. PEAK CURRENT CAPABILITY

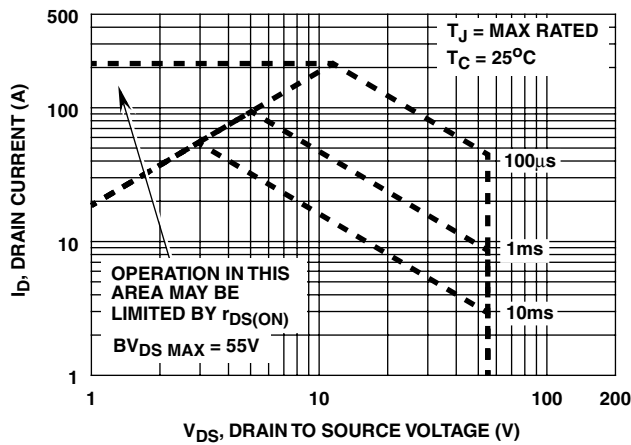
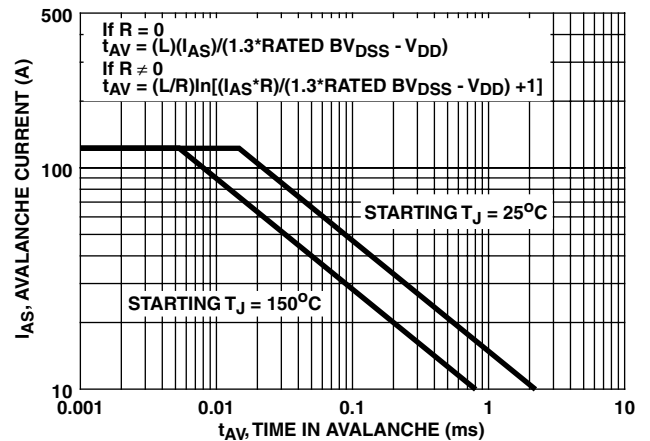


FIGURE 5. FORWARD BIAS SAFE OPERATING AREA



NOTE: Refer to Fairchild Application Notes AN9321 and AN9322.

FIGURE 6. UNCLAMPED INDUCTIVE SWITCHING CAPABILITY

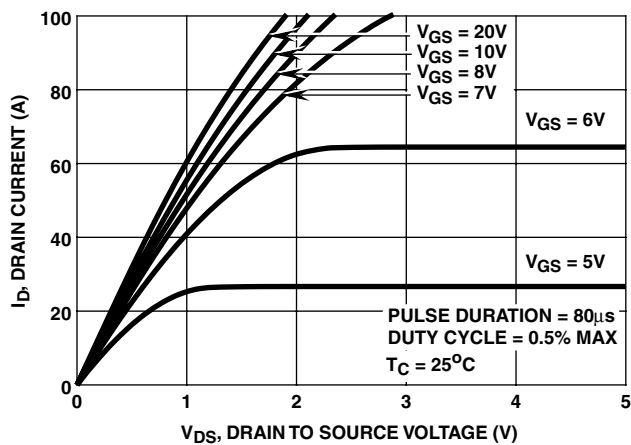


FIGURE 7. SATURATION CHARACTERISTICS

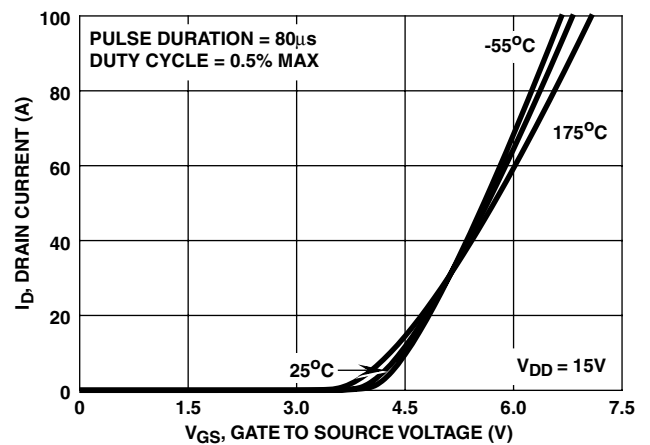


FIGURE 8. TRANSFER CHARACTERISTICS

Typical Performance Curves (Continued)

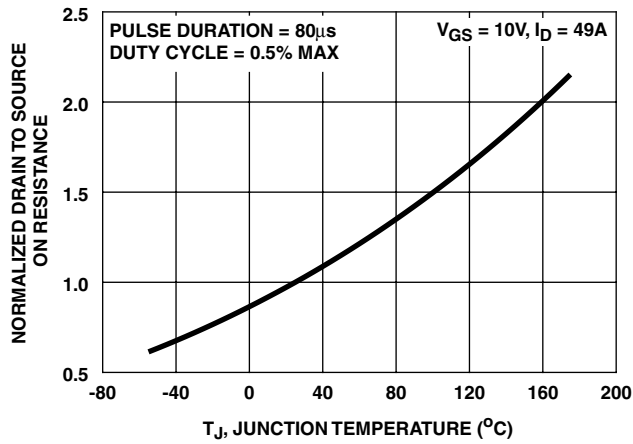


FIGURE 9. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

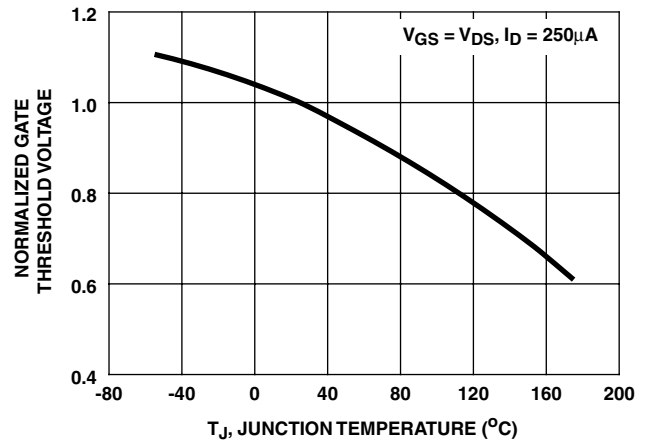


FIGURE 10. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE

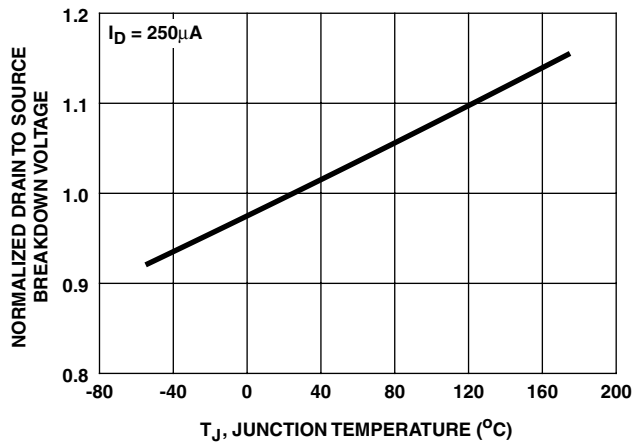


FIGURE 11. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE

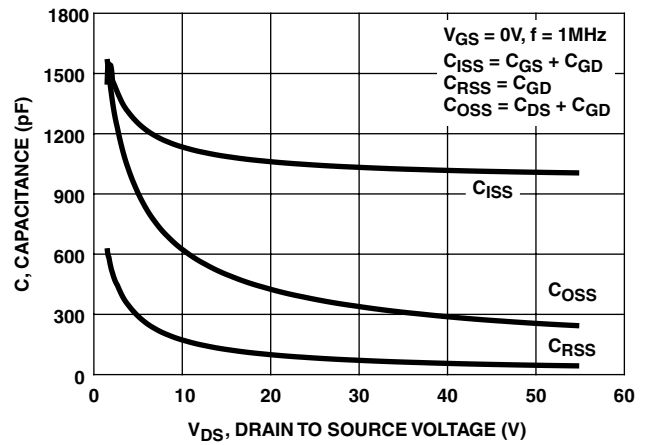
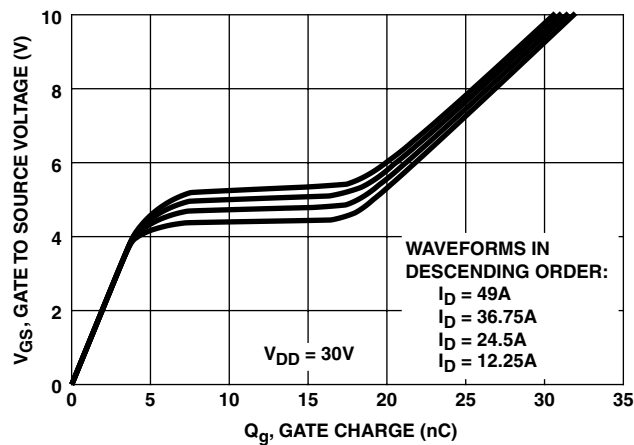


FIGURE 12. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE



NOTE: Refer to Fairchild Application Notes AN7254 and AN7260.

FIGURE 13. GATE CHARGE WAVEFORMS FOR CONSTANT GATE CURRENT

Test Circuits and Waveforms

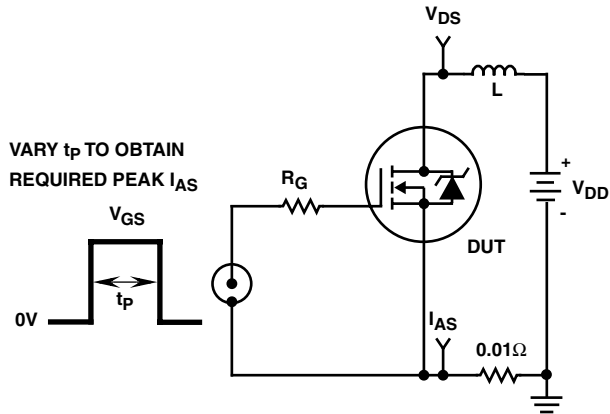


FIGURE 14. UNCLAMPED ENERGY TEST CIRCUIT

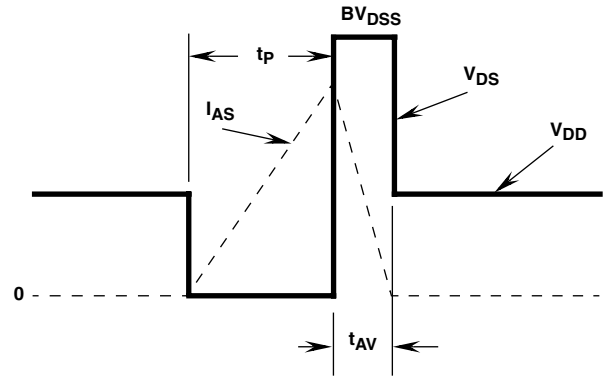


FIGURE 15. UNCLAMPED ENERGY WAVEFORMS

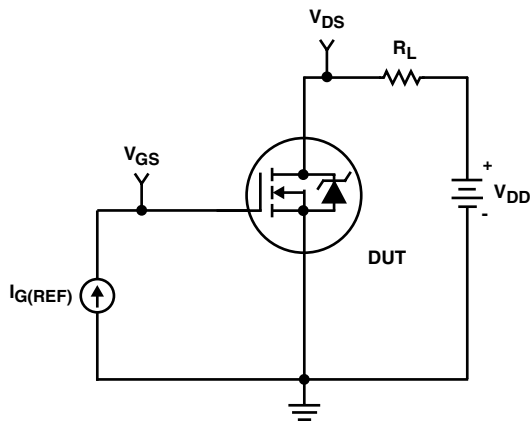


FIGURE 16. GATE CHARGE TEST CIRCUIT

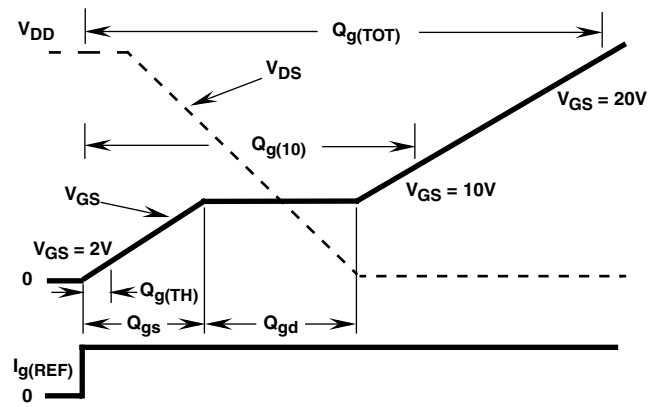


FIGURE 17. GATE CHARGE WAVEFORM

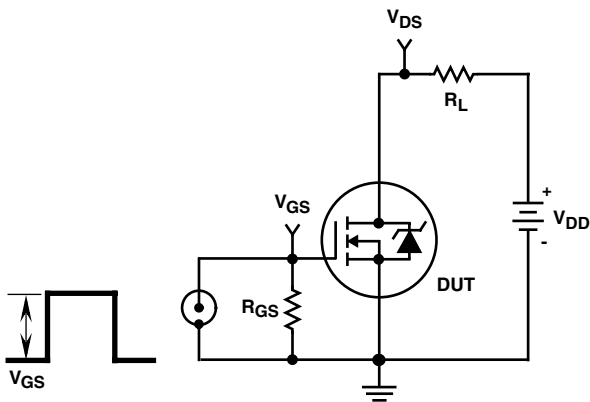


FIGURE 18. SWITCHING TIME TEST CIRCUIT

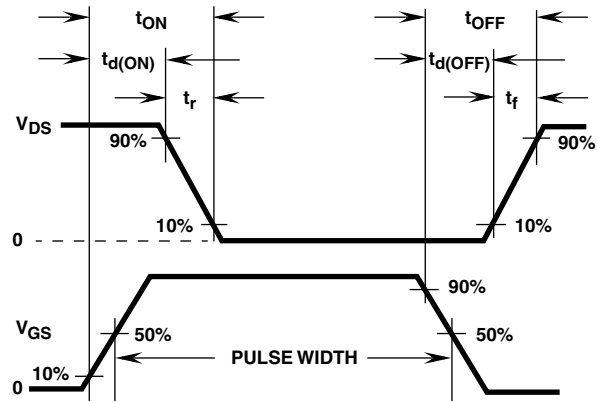


FIGURE 19. RESISTIVE SWITCHING WAVEFORMS

PSPICE Electrical Model

SUBCKT HRFZ44N 2 1 3: rev 6/19/97

CA	12	8	1.72e-9
CB	15	14	1.52e-9
CIN	6	8	9.61e-10

```
DBODY 7 5 DBODYMOD
DBREAK 5 11 DBREAKMOD
DPLCAP 10 5 DPLCAPMOD
```

```
EBREAK 11 7 17 18 58.13
EDS 14 8 5 8 1
EGS 13 8 6 8 1
ESG 6 10 6 8 1
EVTHRES 6 21 19 8 1
EVTEMP 20 6 18 22 1
```

IT 8 17 1

```
LDRAIN 2 5 1e-9
LGATE 1 9 2.86e-9
LSOURCE 3 7 2.69e-9
```

MMED 16 6 8 8 MMEDMOD
MSTRO 16 6 8 8 MSTROMOD
MWEAK 16 21 8 8 MWEAKMOD

```

RBREAK 17 18 RBREAKMOD 1
RDRAIN 50 16 RDRAINMOD 1e-3
RGATE 9 20 1.52
RLDRAIN 2 5 10
RLGATE 1 9 26.9
RLSOURCE 3 7 28.6
RSLC1 5 51 RSLCMOD 1e-6
RSLC2 5 50 1e3
RSOURCE 8 7 RSOURCEMOD 13.85e-3
RVTHRES 22 8 RVTHRESMOD 1
RVTEMP 18 19 RVTEMPMOD 1

```

S1A 6 12 13 8 S1AMOD
S1B 13 12 13 8 S1BMOD
S2A 6 15 14 13 S2AMOD
S2B 13 15 14 13 S2BMOD

VBAT 22 19 DC 1

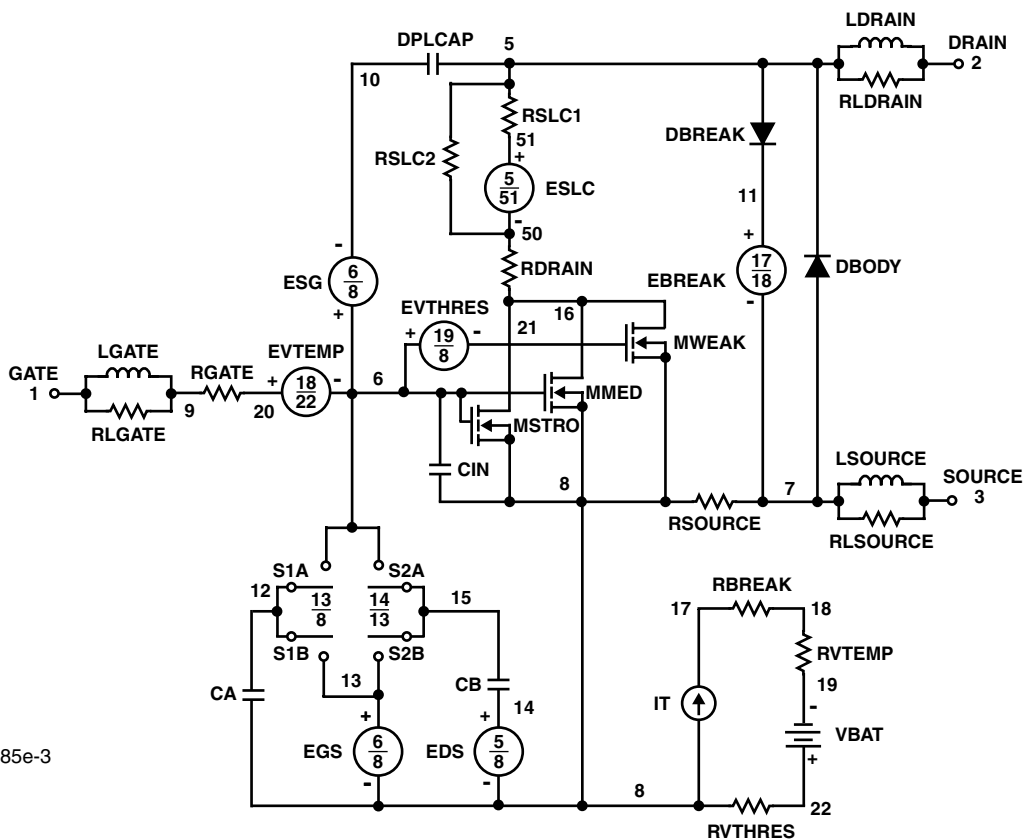
ESLC 51 50 VALUE={ (V(5,51)/ABS(V(5,51))) * (PWR(V(5,51)/(1e-6*135),3.5)) }

```
.MODEL DBODYMOD D (IS = 7.50e-13 RS = 5.05e-3 TRS1 = 2.21e-3 TRS2 = 1.02e-6 CJO = 1.51e-9 TT = 4.05e-8 M = 0.5)
.MODEL DBREAKMOD D (RS = 2.14e-1 TRS1 = 9.62e-4 TRS2 = 1.23e-6)
.MODEL DPLCAPMOD D (CJO = 13.5e-10 IS = 1e-30 N = 10 M = 0.85)
.MODEL MMEDMOD NMOS (VTO = 3.25 KP = 2.50 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u RG = 1.52)
.MODEL MSTROMOD NMOS (VTO = 3.80 KP = 70.0 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u)
.MODEL MWEAKMOD NMOS (VTO = 2.91 KP = 0.06 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u RG = 15.2 RS = 0.1)
.MODEL RBREAKMOD RES (TC1 = 1.05e-3 TC2 = 1.94e-7)
.MODEL RDRAINMOD RES (TC1 = 8.04e-2 TC2 = 1.37e-4)
.MODEL RSLCMOD RES (TC1 = 4.83e-3 TC2 = 1.16e-6)
.MODEL RSOURCEMOD RES (TC1 = 0 TC2 = 0)
.MODEL RVTHRESMOD RES (TC = -3.43e-3 TC2 = -1.63e-5)
.MODEL RVTEMPMOD RES (TC1 = -1.35e-3 TC2 = 1.16e-6)
```

```
.MODEL S1AMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -7.90 VOFF= -4.90)
.MODEL S1BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -4.90 VOFF= -7.90)
.MODEL S2AMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -0.50 VOFF= 2.50)
.MODEL S2BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = 2.50 VOFF= -0.50)
```

.ENDS

NOTE: For further discussion of the PSPICE model, consult **A New PSPICE Sub-Circuit for the Power MOSFET Featuring Global Temperature Options**; IEEE Power Electronics Specialist Conference Records, 1991, written by William J. Hepp and C. Frank Wheatley.



SPICE Thermal Model

REV 23 February 1999

HRFZ44N

CTHERM1 th 6 2.80e-3
 CHERM2 6 5 1.00e-2
 CHERM3 5 4 6.80e-3
 CHERM4 4 3 7.00e-3
 CHERM5 3 2 1.60e-2
 CHERM6 2 tl 15.55

RHERM1 th 6 7.94e-3
 RHERM2 6 5 1.98e-2
 RHERM3 5 4 5.57e-2
 RHERM4 4 3 3.13e-1
 RHERM5 3 2 4.71e-1
 RHERM6 2 tl 6.26e-2

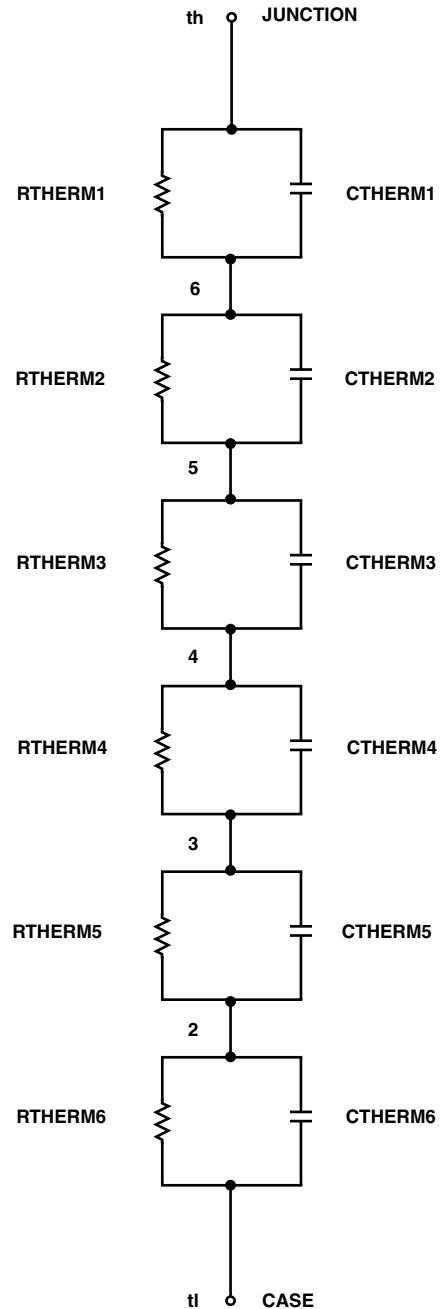
SABER Thermal Model

SABER thermal model HRFZ44N

template thermal_model th tl
 thermal_c th, tl

```
{
    ctherm.therm1 th 6 = 2.80e-3
    ctherm.therm2 6 5 = 1.00e-2
    ctherm.therm3 5 4 = 6.80e-3
    ctherm.therm4 4 3 = 7.00e-3
    ctherm.therm5 3 2 = 1.60e-2
    ctherm.therm6 2 tl = 15.55
```

```
    rtherm.rtherm1 th 6 = 7.94e-3
    rtherm.rtherm2 6 5 = 1.98e-2
    rtherm.rtherm3 5 4 = 5.57e-2
    rtherm.rtherm4 4 3 = 3.13e-1
    rtherm.rtherm5 3 2 = 4.71e-1
    rtherm.rtherm6 2 tl = 6.26e-2
}
```



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DenseTrench™	GTO™	Power247™	SuperSOT™-6	
DOME™	HiSeC™	PowerTrench [®]	SuperSOT™-8	
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E ² CMOS™	LittleFET™	QS™	TinyLogic™	
EnSigna™	MicroFET™	QT Optoelectronics™	TruTranslation™	
FACT™	MicroPak™	Quiet Series™	UHC™	
FACT Quiet Series™	MICROWIRE™	SILENT SWITCHER [®]	UltraFET [®]	

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